



# LOCTITE<sup>®</sup> ABLESTIK CF 3366 HIGH-TEMPERATURE STABLE, SILVER-FILLED FILM ADHESIVE

*LOCTITE*<sup>®</sup> *ABLESTIK* CF 3366 is an epoxy-based, silver-filled film adhesive with high thermal and electrical conductivity designed for high-reliability applications such as those found in the aerospace sector. Within harsh conditions, *LOCTITE ABLESTIK* CF 3366 maintains its adhesion strength up to temperatures as high as 175°C, facilitating reliable thermal and electrical performance even during extended exposure to elevated temperatures. Available in custom-cut dimensions, *LOCTITE ABLESTIK* CF 3366 offers a clean, low cost-of-ownership alternative to paste adhesives.





## **Key Benefits**

- **High and stable adhesion at elevated temperatures** maintains adhesion strength up to temperatures as high as 175°C; capable in extreme environments
- **High electrical and thermal conductivity** outstanding grounding and minimum thermal resistance to heat sink
- Compatible with temperature-sensitive substrates and components cures at a low temperature of 125°C
- Flexible allows use of material combinations with CTE mismatches
- **Customized preforms** can be custom cut to accommodate highly complex dimensions for clean, easy application with no waste







LOCTITE ABLESTIK CF 3366 film adhesive is formulated for electrical, thermal and mechanical high-temperature assembly applications. The combination of adhesive properties ensures reliable RF ground plane performance suitable for extreme environmental conditions.

TYPICAL PROPERTIES OF UNCURED MATERIAL		
Peak Exotherm Temperature (DSC) Ramp Rate, 10°C/min.	165°C <u>+</u> 5°C	
Work Life at 25°C (days)	91	
Shelf Life at 5°C (days)	183	

TYPICAL CURING PERFORMANCE		
Cure Schedule at 150°C (min.)	60	
Cure Schedule at 125°C (min.)	120	
Cure Pressure	10 to 60 psi	

Across the Board, Around the Globe.		
Around the Globe.		
henkel-adhesives.com/electronics		

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TYPICAL PROPERTIES OF CURED MATERIAL		
Glass Transition Temperature, Tg (pp	m/°C)	190
Coefficient of Thermal Expansion (ppm/°C)	Below Tg:	85
	Above Tg:	195
Storage Modulus, DMA	25°C (N/mm²)	4,500
	100°C (N/mm²)	2,500
	150°C (N/mm²)	900
Volume Resistivity (Ω∙cm at 25°C)		0.0003

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